

HYBOND

Soft Touch™

MODEL 616B-001 ULTRASONIC PEG BONDER

For 0.5 - 2.0 mil (12.5 - 50 micron) dia. insulated wire, 0.5 - 3.0 mil (12.5 - 75 micron) dia. bare wire and up to 1 x 20 mil (25 x 500 micron) gold or aluminum wire, ribbon or gold plated copper leads



STANDARD FEATURES:

- ! HYBOND *Soft Touch* bond force system.
- ! Servo-motor vertical (Z axis) control.
- ! 1.0 inch vertical bonding window.
- ! Variable height bonding within 1.0 inch.
- ! Search height adjustable in 0.001 inch increments.
- ! Hi/Lo U/S power selector (PLL generator).
- ! Digital parameter adjustment in actual units (watts, milliseconds and grams).
- ! Storage for up to ten bond schedules in non-volatile memory.
- ! Wiring for 120VAC 50/60 Hz @ 10A max.
- ! Dual bond counters record number of bonds performed by bonding tool and total bonds.
- ! Dual footswitch control for bond head vertical (up and down) movement.
- ! Bond head vertical movement can be controlled in fast or slow speeds on manual mode.
- ! Bond level sensor system stops Z axis movement upon contact with bond surface and activates bond cycle.
- ! Deep access when using 0.750 inch tool.

HYBOND's Model 616B-001 ultrasonic single channel peg bonder is designed for ultrasonic bonding of interconnects in applications that do not require the bonder to feed wire. Applications include "tacking" tuning ribbons, insulated wire bonding, flex on flex bonding, pin tab bonding, mesh bonding and ball coining. When fitted with a WP-260 motorized work platform, the 616B-001 becomes a semiautomatic bonder for medium to high volume production.

Partial List of Available Options:

- ! **OP-06S6:** Leica S6 Zoom Stereo Microscope.
- ! **OP-06A:** Nikon SMZ660 Microscope.
- ! **OP-08A:** Dual Fiber Optic Illuminator.
- ! **OP-08R-LED:** White LED Ring Illuminator.
- ! **OP-12:** Provisions for 240VAC 50/60 Hz operation.
- ! **OP-30:** 8:1 Ratio X-Y Manipulator.
- ! **OP-47:** Beam Lead Diode Bonding option.
- ! **WP-260:** Motorized programmable X-Y Platform. Connects to bonder for automatic bond sequencing, joy stick control/user interface to set 1st pad location.
- ! **WP-CF:** Work platform with custom fixture.
- ! **Work Stages** (Heated & Unheated) available.
- ! **PT-X.X:** Peg Tool as ordered per application.

Specifications for Model 616B-001:

- ! Ultrasonic (U/S) System: PLL self tuning 62.5KHz (nominal) system (± 2.5 KHz).
- ! U/S Power Range: 0-0.2 watt on low setting and 0-4 watts on high setting.
- ! Bond Time Range: 0mSec. to 900mSec.
- ! Bond Force Range: 12gr. to 300gr.
- ! Bondable Wire Diameter: 0.7 to 3.0mil (18 to 76 μ m).
- ! Bond Head Movement: True vertical motorized movement with fast and slow speeds in manual mode or search height pause in auto mode
- ! Bond Actuation: Bond height sensor activates bond cycle upon contact with bond Surface/overtravel.
- ! Input Power Requirements: 120VAC 50/60Hz @ 10A (max.) is standard, order OP-12 for 240VAC 50/60Hz.
- ! Minimum Bench Space Required: Width: 20 in., Depth: 20 in. (50,8cm x 50,8cm).
- ! Unit Weight: 45 lbs. (20Kg).
- ! Shipping Weight: 135 lbs. (61,2Kg), shipping weight varies with options ordered.
- ! Industry Standards: CE.

For more information contact us:



330 State Place, Escondido, CA. 92029, USA

Tel. 760-746-7105 Fax. 760-746-1408

e-mail: mailus@hybond.com or visit us online at: www.hybond.com